Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

NICROCHIP Semiconductor Device Type: H8A 006 VDFN 7x5x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
		"Contained In" Sub-Component	% Total Weight			46.31	(mg) Total	Mold Compound	% ot Total Weight	56.27
Basic Substance	CAS Number	•		mg/part	ppm		,	·		
Silica, fused Epoxy Resin	60676-86-0 Trade Secret	Mold Compound Mold Compound	50.643 2.729	41.679 2.246	506,430 27,291		Silica, fused Epoxy Resin	60676-86-0 Trade Secret	90.00 4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.729	2.246	27,291		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.169	0.139	1,688	1	Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	39.445	32,464	394.454			Total	100.00	
Iron	7439-89-6	Lead Frame	0.932	0.767	9,324	33.36	(mg) Total	Lead Frame	% of Total Weight	40.54
Zinc (Metal)	7440-66-0	Lead Frame	0.101	0.083	1,014		Copper	7440-50-8	97.30	
Phosphorous	7723-14-0	Lead Frame	0.061	0.050	608		Iron	7439-89-6	2.30	
Silver	7440-22-4	Die Attach	0.225	0.185	2,250	1	Zinc (Metal)	7440-66-0	0.25	
Methacrylic acid, isobornyl ester	7534-94-3	Die Attach	0.042	0.035	420		Phosphorous	7723-14-0	0.15	
1,3-Bismaleimidobenzene	3006-93-7	Die Attach	0.023	0.019	225			Total	100.00	
polymer with oxirane mono-2-propenoate	1017237-78-3	Die Attach	0.011	0.009	105	0.25	(mg) Total	Die Attach	% of Total Weight	0.30
Silicon	7440-21-3	Chip (Die)	1.460	1.202	14,600		Silver	7440-22-4	75.00	
Gold	7440-57-5	Wire Bond	0.250	0.206	2,500	Metha	acrylic acid, isobornyl ester	7534-94-3	14.00	
Nickel	7440-02-0	Plating on external leads (pins)	1.112	0.915	11,118		1,3-Bismaleimidobenzene	3006-93-7	7.50	
			0.043	0.035	426	polymer with o	xirane mono-2-propenoate	1017237-78-3	3.50	
Palladium	7440-05-3	Plating on external leads (pins)		0.055	720					
	7440-05-3 7440-57-5	Plating on external leads (pins) Plating on external leads (pins)	0.026	0.021	256	. ,	Andrio mono E propondato	Total	100.00	
Palladium						1.20	Total (mg)		100.00 % of Total Weight	1.46
Palladium Gold miconductor device and its homogenous materia 63/EU (31 March 2015) and 2002/53/EC (End-of-Li	7440-57-5 0.0823 als comply with E ife Vehicles (ELV)	Plating on external leads (pins) TOTALS: g Total Mass U Directives: 2002/95/EC (27 January 2003) & Dir without exemption (zero)	0.026 100.000 rective 2011/65/	0.021 82.300 /EU (08 June 2	256 1,000,000		Total (mg) Doped Silicon	Total Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	
Palladium Gold miconductor device and its homogenous materia 63/EU (31 March 2015) and 2002/53/EC (End-of-Li ance with the above EU Directives has been verificant substance is absent from the list above, the	7440-57-5 0.0823 als comply with Eife Vehicles (ELV) fied via internal de	Plating on external leads (pins) TOTALS: g Total Mass U Directives: 2002/95/EC (27 January 2003) & Dir without exemption (zero) esign controls, supplier declarations, and /or analyance is NOT an intentional ingredient in the semic	0.026 100.000 rective 2011/65/ ytical test data.	0.021 82.300 /EU (08 June 2	256 1,000,000 2011) and	0.21	Total (mg) Doped Silicon (mg) Total	Total Chip (Die) 7440-21-3 Total Wire Bond	% of Total Weight 100.00 100.00 % of Total Weight	0.25
Palladium Gold emiconductor device and its homogenous materic 63/EU (31 March 2015) and 2002/53/EC (End-of-Li iance with the above EU Directives has been veri emical substance is absent from the list above, the hip Technology Incorporated's knowledge and be ntration of the chemical substance, if any, is not be	7440-57-5 0.0823 als comply with E fe Vehicles (ELV) fied via internal de the chemical substable as of the date below the thresho	Plating on external leads (pins) TOTALS: g Total Mass U Directives: 2002/95/EC (27 January 2003) & Dir without exemption (zero) esign controls, supplier declarations, and /or analy ance is NOT an intentional ingredient in the semic of this document, there is no credible reason to I do fregulatory concern for any regulatory schem	0.026 100.000 rective 2011/65, ytical test data. conductor device believe that the ne world-wide.	0.021 82.300 /EU (08 June 2 ce and, to the le unavoidable	256 1,000,000 2011) and best of impurity		Total (mg) Doped Silicon	Total Chip (Die) 7440-21-3 Total Wire Bond 7440-57-5	% of Total Weight 100.00 100.00 % of Total Weight 100.00	
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